SoundPower

ULTEX

Application

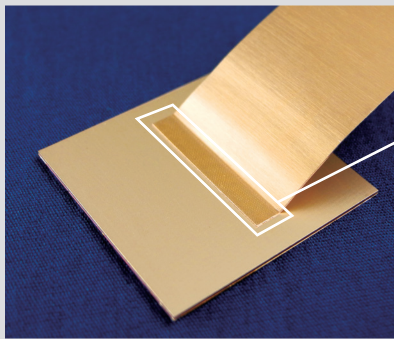
https://ultex.co.jp

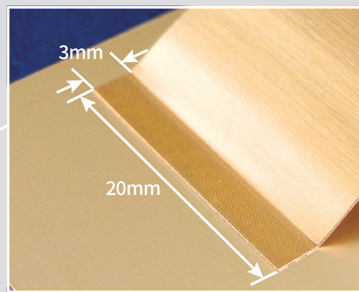
Bonding ボンディング

FR4基板上へのFFCの接合

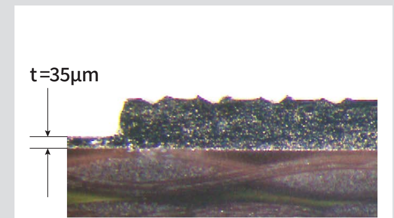
全面／5箇所一括同時音波接合

All area



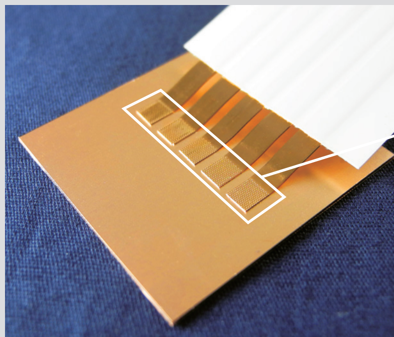


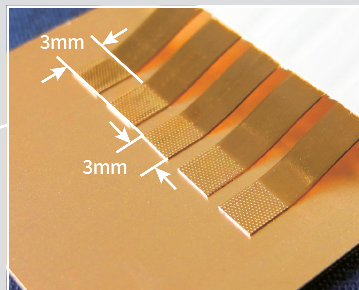
FR4 substrate : t=0.3mm, Cu layer : t=35μm
Cu foil : t=0.1mm



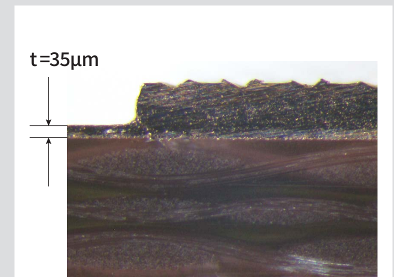
The cross section

5points





FR4 substrate : t=0.3mm, Cu layer : t=35μm
Cu foil : t=0.15mm



The expanded cross section

Product used 使用する装置

15MZs

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